# HOTINTERCONNECTS

**SPONSORSHIP PLANS 2025** 





#### **HOTI 2024**

IEEE Symposium on High-Performance Interconnects 21-23 August 2024 • Virtual, United States

#### **ABOUT HOTI**

forum for researchers and developers of state-of-the-art hardware and software architectures and implementations for interconnection networks that scale from between chiplets to across a data center

Leaders in industry and academia attend the conference to interact with individuals at the forefront of this field



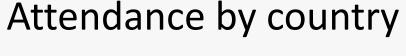


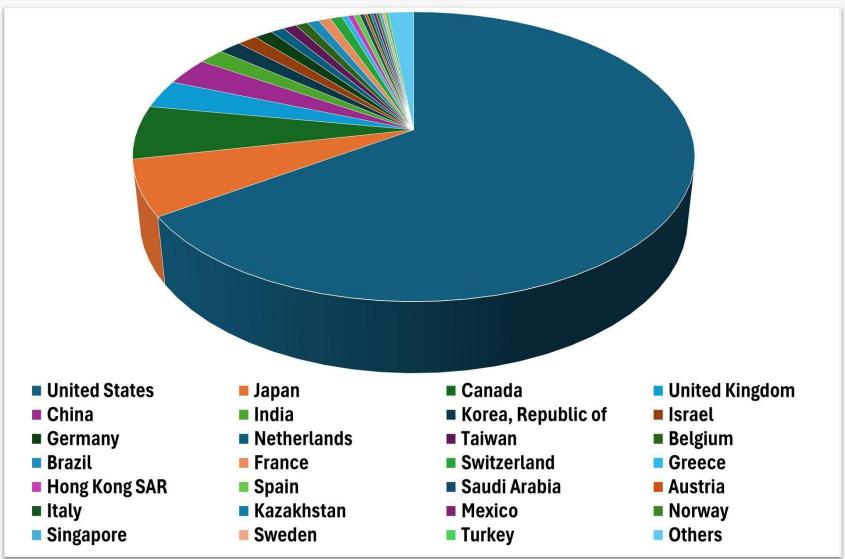
# **HOTI 2024 IN NUMBERS**

- Peer-reviewed paper submission
  - 27% full paper acceptance rate
- Significant attendance
  - >1100 zoom registrations
  - >900 attendees
  - 81% attendance/registration
  - 44 countries
  - 500 organizations
- 7 tutorials from industry and academia:



















#### **HOTI Publications and Statistics**

#### **Publications:**

- Two paper formats supported:
  - Hot topic short papers (3-4 pages)
  - Full length papers (6-8 pages)
- HOTI papers published to IEEE Xplore (All previous HOTI proceedings here)
- A best paper award presented in both industry and academia categories
- Best papers selected for the IEEE Micro special issue (2023 edition here)





#### **Statistics and Rankings:**

- LiveSHINE and Microsoft Academic give HOTI an A ranking w/ 19-20 average citations per paper
- DBLP reports over 14 citations per paper (see live DBLP database query here)
- ICORE ranks with approximately a B citation ranking (ICORE HOTI, CORE2023 citations)



#### **PREVIOUS SPONSORS**

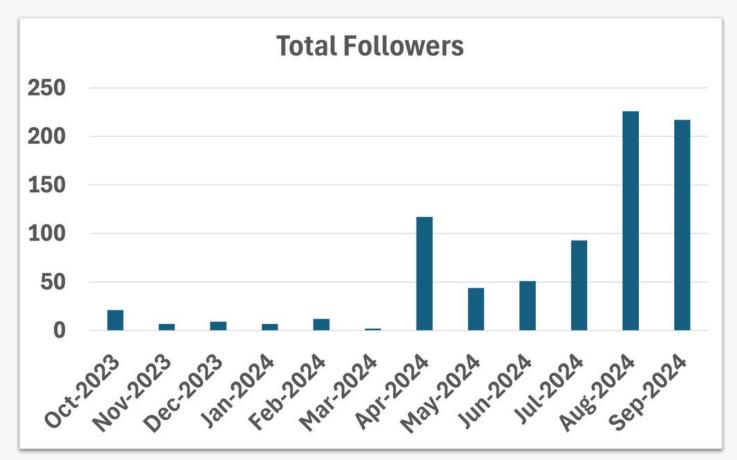
2023

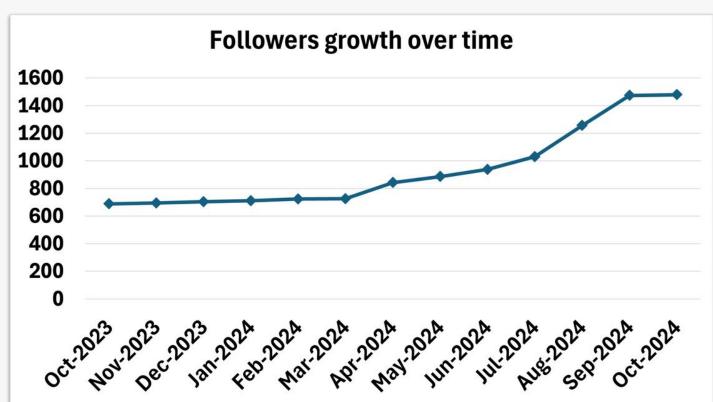


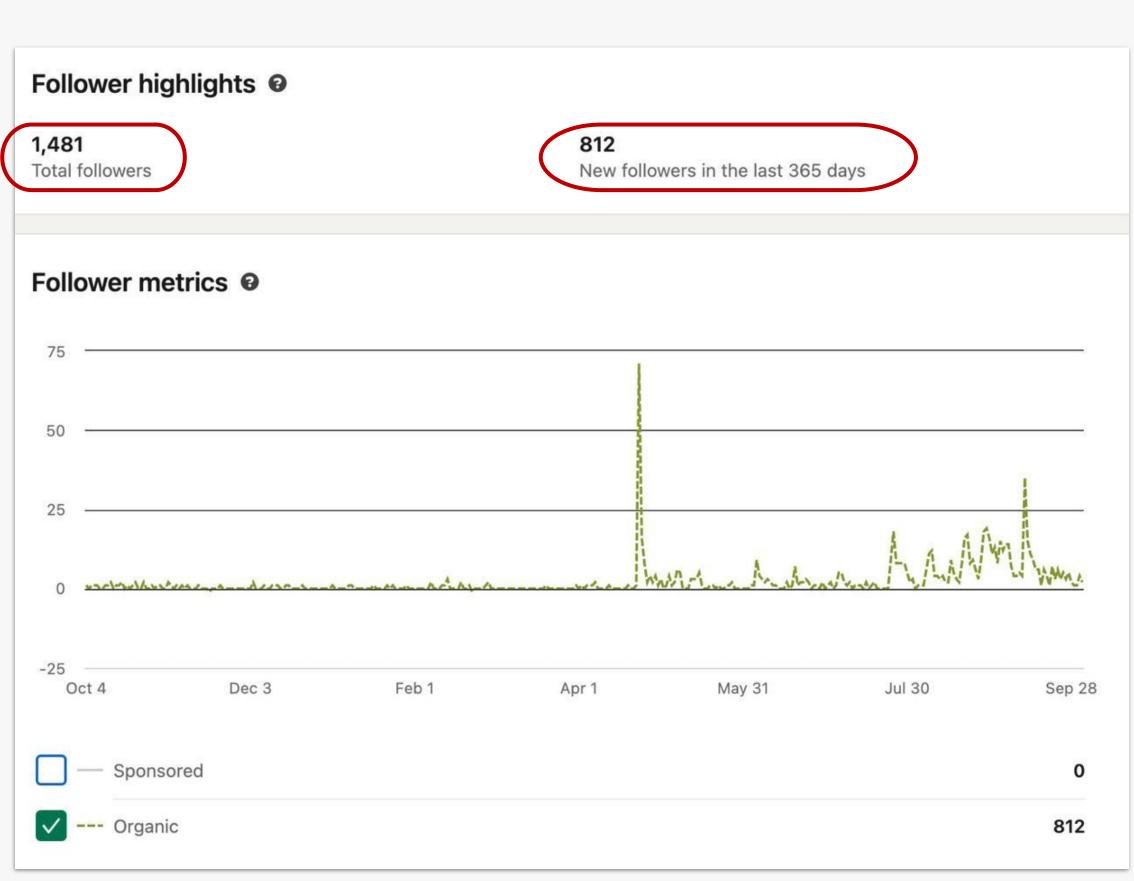




#### **LINKEDIN ANALYTICS - FOLLOWERS**

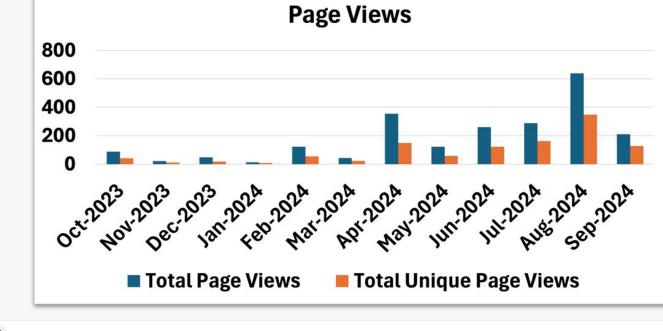


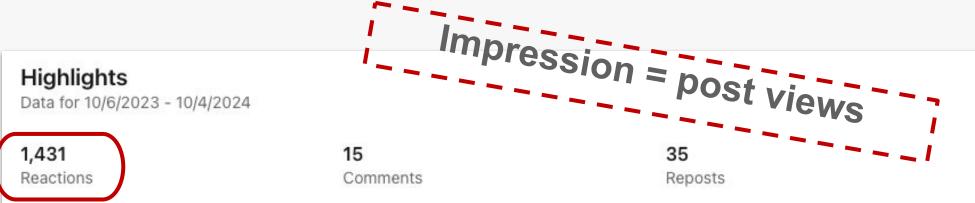


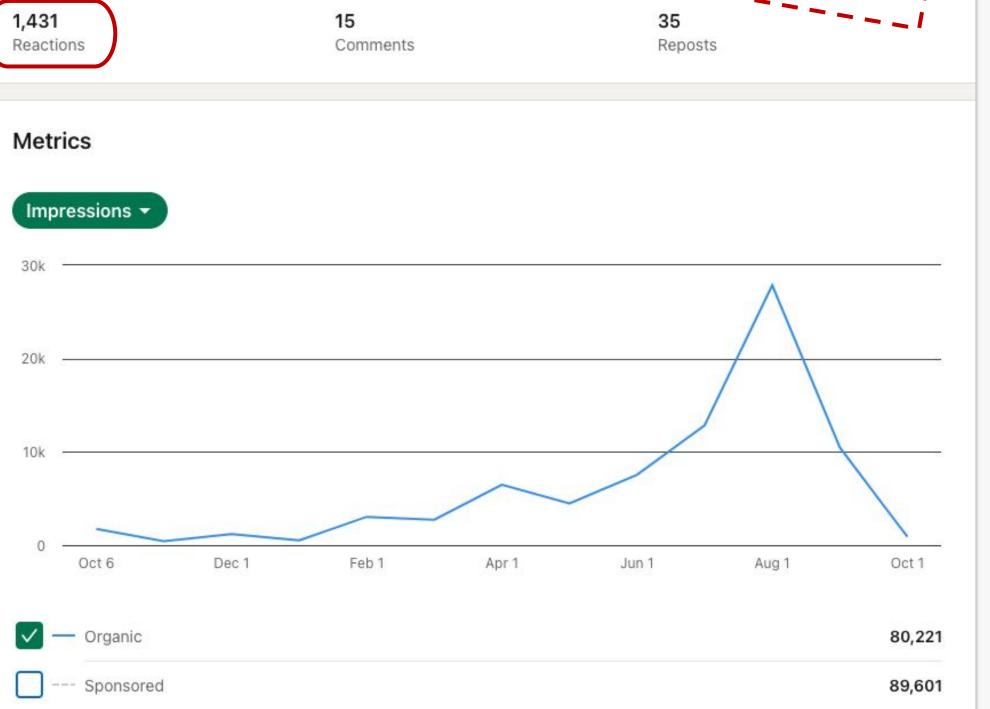


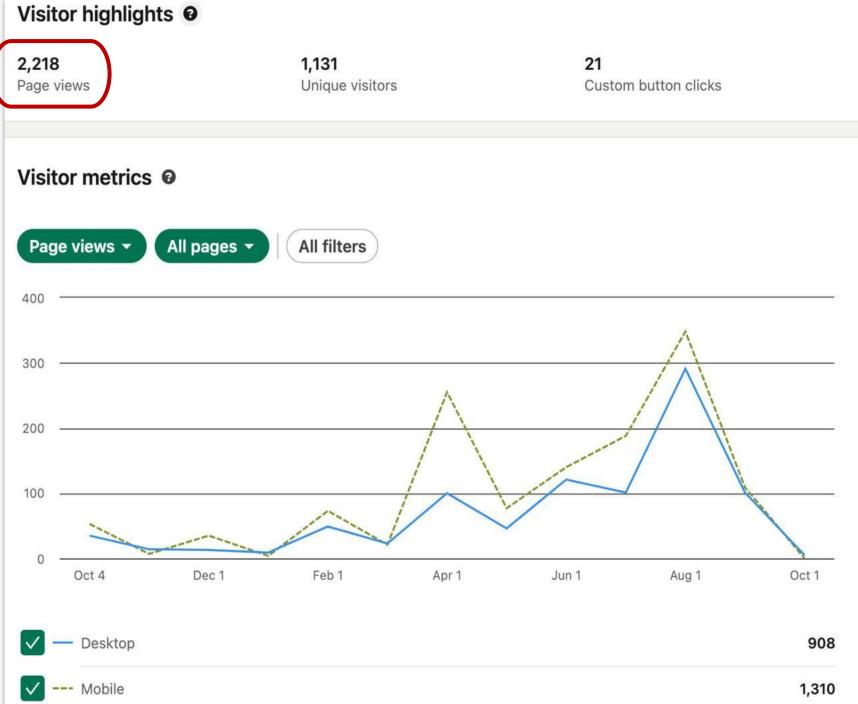


### **LINKEDIN ANALYTICS**



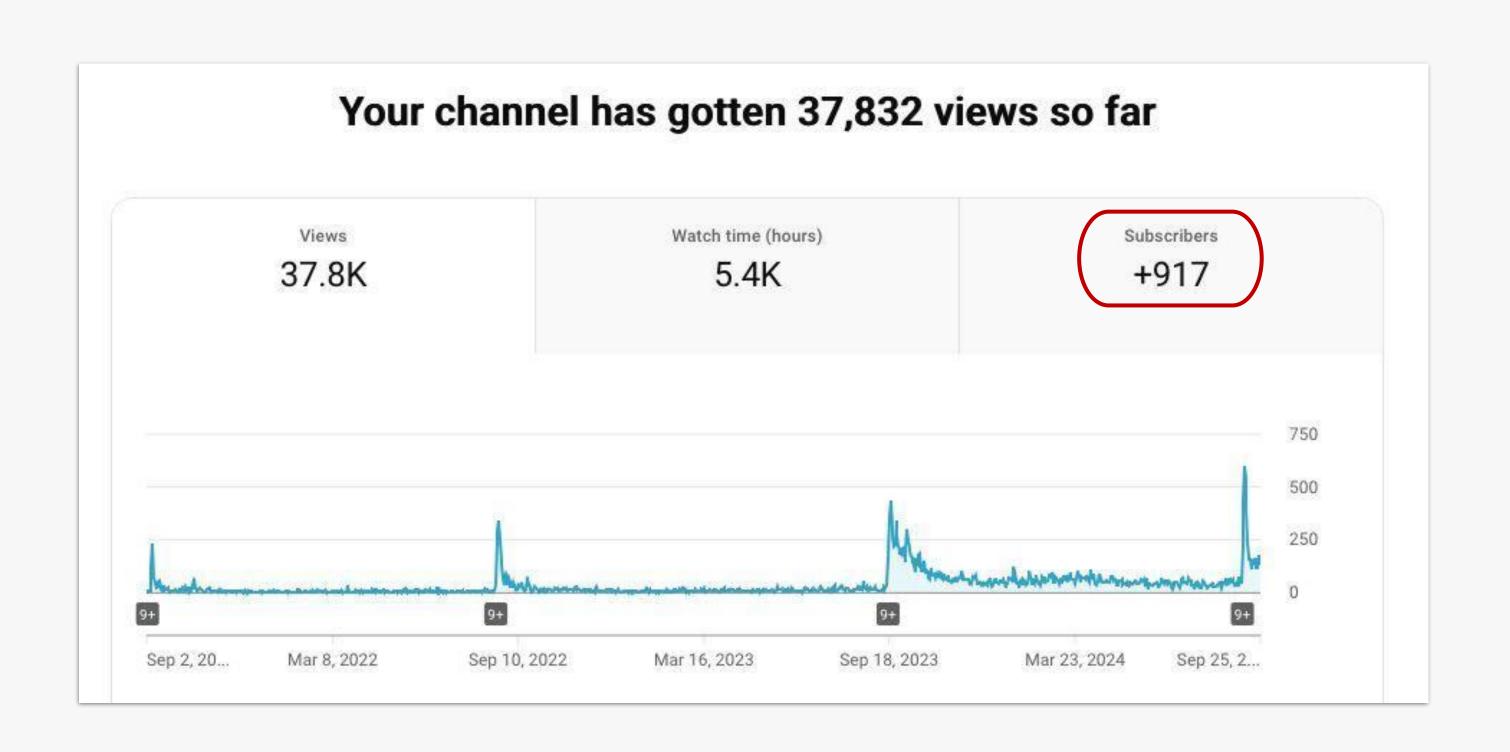








## **YOUTUBE ANALYTICS**





## 2025 Conference Theme

## Interconnect Software: You can't touch it, but you need it

The latest advancements in photonics, chips, parallel paths, and other cutting-edge interconnect technologies are dazzling. However, the picture is incomplete without the system software needed to exploit their full potential. This edition of Hot Interconnects will explore the underlying software ecosystems that empower interconnect fabrics to support a wide array of applications.



# **SPONSORSHIP LEVELS 2025**

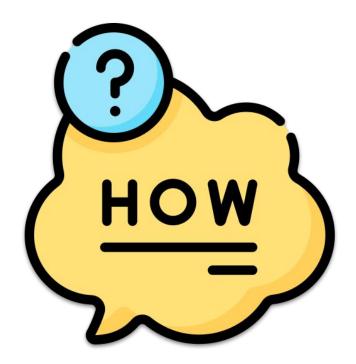
Plan		Cost	Speaking Slot Time	Email Distribution	Sponsor Logo	Recording	Splash Screen
INTERCONNECTS	Diamond	\$4000	15 min	up to 59K Recipients (3 times)	Jumbo	Yes	Yes
INTERCONNECTS	Platinum	\$3000	10 min	up to 59K Recipients (3 times)	Large	Yes	Yes
INTERCONNECTS	Gold	\$2000	5 min	up to 59K Recipients (3 times)	Medium	Yes	Yes
INTERCONNECTS	Silver	\$1000	N/A	up to 59K Recipients (3 times)	Small	N/A	No



#### **HOW TO BECOME A SPONSOR**

#### Becoming a sponsor:

- Step 1. Select a sponsorship level
- Step 2. Send an email to: sponsor@hoti.org
- Step 3. Make sponsor payment



#### **Benefits:**

- A dedicated presentation slot (recording or live) during the conference with a targeted audience interested in network interconnect technologies
- Sponsor logos displayed during conference (in breaks)
- Logo displayed on the website throughout 2025 (starting from the time of becoming a sponsor)
- **Visibility** on official **Hot Interconnects** social media channels (LinkedIn, X/Twitter and Facebook)
- Detailed statistics of conference attendance provided after the event



# Thank you!

Questions? sponsor@hoti.org